



Linear Low Density Polyethylene IC32

Description:

IC32 is a linear low-density polyethylene, with narrow molecular weight, produced by solution process, for injection molding. It offers good fluidity, excellent flexibility, tenacity and low warpage. It contains special antioxidant additives.

Application:

Resin has been specifically developed for lids molding injection, house appliances and master batch production.

Control Properties:

	ASTM Methods	Units	Values
Melt Flow Rate (190/2.16)	D 1238	g/10 min	29
Density	D 729	g/cm ³	0.924

Typical Properties:

Plaque Properties^a

	ASTM Methods	Units	Values
Tensile Strength at Yield	D 638	MPa	12
Tensile Strength at Break	D 638	MPa	9
Tensile Modulus – 1% Secant	D 790	MPa	350
Tensile Elongation at Break	D 638	%	250
Environmental Stress Cracking Resistanceb	D 1693	h/F50	-
Vicat Softening Temperature at 10 N	D 1525	°C	1
Rigidity	D 747	MPa	320
Fragility Temperature	D 746	°C	<-70

⁽a) Test specimens prepared from compression molded sheet made according to ASTM D 4703.

Recommended Processing Conditions:

The IC32 resin has been developed to be used in injection molding, in similar conditions to the other Linear Low Density Polyethylene of similar fluidity.

Recommended temperature profile: 150 to 200°C.

Final Remarks:

- 1. This resin meets the requirements for olefin polymers as defined in 21 CFR, section 177.1520 issued by FDA Food and Drug Administration in force on the date of publication of this specification. The additives present are covered in appropriate regulation by FDA
- 2. The information presented in this Data Sheet reflects typical values obtained in our laboratories, but should not be considered as absolute or as warranted values. Only the properties and values mentioned on the Certificate of Quality are considered as guarantee of the product.
- In some applications, Braskem has developed tailor-made resins to reach specific requirements.
 In case of doubt regarding utilization, or for other applications, please contact our Technical Assistance.
- 5. For information about safety, handling, individual protection, first aids and waste disposal, please see MSDS. CAS Registry number: 25087-34-7.
- 6. The mentioned values in this report can be changed at any moment without Braskem previous communication.
- Braskem does not recommend this grade for packages, parts or any kind of product manufacture that will be used for storage or contact with solution that will have internal contact with human body.
- The content of this Data Sheet replaces previous revisions published for this product.
- 9. This resin does not contain the substance Bisphenol A (BPA, CAS # No. 80-05-7) in its composition.





⁽b) Compression molded 2 mm thickness, 0.3 mm notched-plaques; 10% Igepal; 50°C.